



Title of Change:	ON Semiconductor is expanding assembly capacity via qualifying external package/assembly subcontractor. Applicable to the family of products (and related OPNs) NCP3230, NCP3231A, NCP3231, NCP3232, NCP3233, NCP3235 and NCP5339.							
Proposed first ship date:	10 August 2018 <i>or earlier upon customer approval.</i>							
Contact information:	Contact your local ON Semiconductor Sales Office.							
Samples:	Contact your local ON Semiconductor Sales Office.							
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCEN) sent to customers. IPCENs are issued at least 30 days prior to the issuance of the Final Change Notice (FCEN). An IPCEN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FCEN). This IPCEN notification will be followed by a Final Product/Process Change Notification (FCEN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>							
Change Part Identification:	Parts can be identified through date code marking following ON Semiconductor standards. Contact your local ON Semiconductor Sales Office for the specific date code information.							
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other : _____							
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____							
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Sub con Sites: Advanced Semiconductor Engineering (ASE), Penang, Malaysia						
Description and Purpose:								
Reason:								
ON Semiconductor is expanding the subject products assembly capacity via addition of external assembly subcontractor in the supply chain.								
There is no change to the datasheet specifications, or any other aspect of the product.								
<table border="1"> <thead> <tr> <th>Item to be changed:</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Addition of Product Assembly Site</td> <td>ON Semiconductor, Seremban, Malaysia (Internal Assembly Facility)</td> <td> After the change, Assembly will be done in two locations: <ol style="list-style-type: none"> ON Semiconductor, Seremban, Malaysia Advanced Semiconductor Engineering (ASE), Penang, Malaysia (subcontractor) </td> </tr> </tbody> </table>			Item to be changed:	Before Change Description	After Change Description	Addition of Product Assembly Site	ON Semiconductor, Seremban, Malaysia (Internal Assembly Facility)	After the change, Assembly will be done in two locations: <ol style="list-style-type: none"> ON Semiconductor, Seremban, Malaysia Advanced Semiconductor Engineering (ASE), Penang, Malaysia (subcontractor)
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Qualification Plan:

QV Device Name: NCP3231AMNTXG, NCP3235MNTXG, NCP5339MNTXG

Test	Specification	Condition	Interval	Sample Size	# lots
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	84	1+control
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	84	1+control
HAST	JESD22-A110	130°C, 85% RH, bias	96 hrs	84	1+control
PC	J-STD-020 JESD-A113	MSL 1 @ 85°C/85%RH, 168 Hr 260C reflow All lots prior to HAST, TC	Prior to HAST, TC	All samples	All Qual lots
SAT	J-STD-035	Scanning Acoustic Tomography	Pre and Post PC	5	1
RSH	J-STD-020	Resistance to Solder Heat test		10	1
ED	ON Data Sheet	Electrical Distribution		30	1

Estimated date for qualification completion: 19 April 2018

List of Affected Standard Parts:

Part Numbers	Qualification Vehicle
NCP3230MNTXG	NCP3231AMNTXG NCP3235MNTXG NCP5339MNTXG
NCP3231MNTXG	
NCP3231AMNTXG	
NCP3232NMNTXG	
NCP3233MNTXG	
NCP5339MNTXG	
NCP3235MNTXG	

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
NCP3230MNTXG		NCP3231A, NCP3235 AND NCP5339
NCP3231AMNTXG		NCP3231A, NCP3235 AND NCP5339
NCP3231MNTXG		NCP3231A, NCP3235 AND NCP5339
NCP3232NMNTXG		NCP3231A, NCP3235 AND NCP5339
NCP3233MNTXG		NCP3231A, NCP3235 AND NCP5339
NCP3235MNTXG		NCP3231A, NCP3235 AND NCP5339
NCP5339MNTXG		NCP3231A, NCP3235 AND NCP5339